## **Panasonic**

# **MA6X125** (MA125)

### Silicon epitaxial planar type

For switching circuit

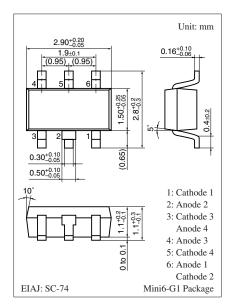
#### ■ Features

 Four isolated elements contained in one package, allowing highdensity mounting

### ■ Absolute Maximum Ratings $T_a = 25$ °C

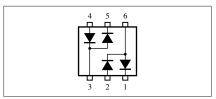
Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	40	V
Maximum peak reverse voltage	$V_{RM}$	40	V
Forward current *	$I_{F}$	100	mA
Peak forward current *	$I_{FM}$	200	mA
Junction temperature	Tj	150	°C
Storage temperature	$T_{stg}$	-55 to +150	°C

Note) \*: Value for single diode



Marking Symbol: M2I

### Internal Connection

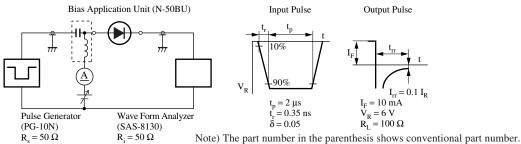


# ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

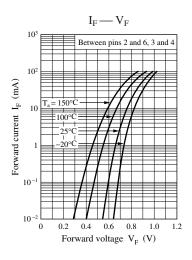
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	$V_F$	$I_F = 100 \text{ mA}$			1.2	V
Reverse voltage	V <sub>R</sub>	$I_R = 100 \mu A$	40			V
Reverse current	$I_R$	$V_R = 40 \text{ V}$			100	nA
Terminal capacitance	C <sub>t</sub>	$V_R = 0 V, f = 1 MHz$			5.0	pF
Reverse recovery time *3	t <sub>rr1</sub> *1	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}$		150		ns
	t <sub>rr2</sub> *2	$I_{rr} = 0.1 I_R, R_L = 100 \Omega$		9		

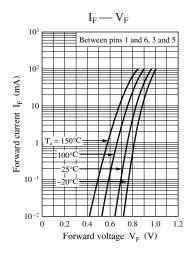
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

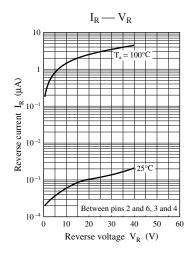
- 2. Absolute frequency of input and output is 100 MHz.
- 3. \*1: Between pins 1 and 6, Between pins 3 and 5
  - \*2: Between pins 2 and 6, Between pins 3 and 4
  - \*3: t<sub>rr</sub> measurement circuit

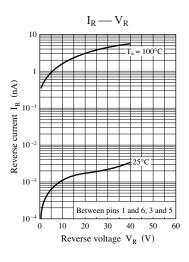


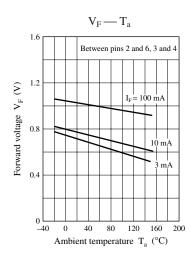
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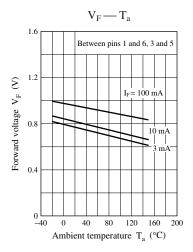


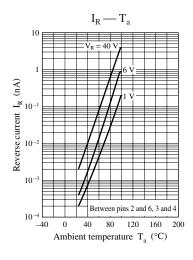


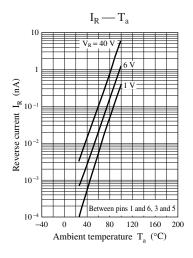


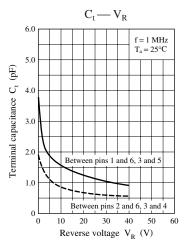




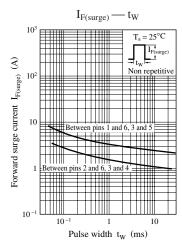








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